

FEATURES

- 45 mΩ High-Side MOSFET
- 1.0~4.0 A (typ.) Adjustable Current Limit
- Low Average Current in OUT shorted GND
- Support Apple® Devices fast charging (Apple® 2.1A / 2.4A mode)
- Support Samsung Galaxy Tab Devices fast Charging
- Support BC1.2 & YD/T 1591-2009 Charging Spec
- Built-in Soft-Start
- Support single layer PCB layout.
- 4.5 ~ 6.5V Single Supply Operation.
- Available EMSOP8, ESOP8 package.

APPLICATIONS

- USB Charger
- USB Wall Adapter
- Car Charger

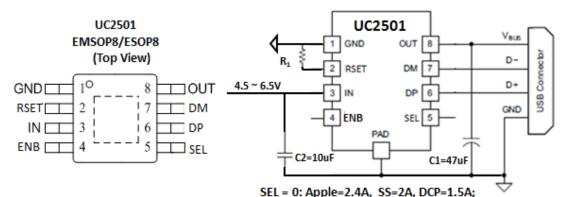
DESCRIPTION

The UC2501 integrated USB charger emulators with automatic host charger identification circuitry and high performance adjustable current limiting power switch. An automatic USB charger identification circuit allows mobile power supply can automatically provides the correct modes on the data lines to charger compliant devices among the Apple, Samsung and BC1.2 modes.

The UC2501 is a $45m\Omega$ power switch intended for applications where heavy capacitive loads and short-circuits are likely to be encountered. This also provides hiccup mode when OUT voltage is less than 2.85V or OTSD.

The UC2501 provides an ENB pin to turn on or turn off UC2501 and an SEL pin to select 10W or 12W mode in application.

PACKAGE AND APPLICATION



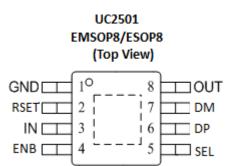
SEL = 1 or Floating: Apple=2.1A, SS=2A, DCP=1.5A; ENB is floating or pull down with 10k Resistor if not used

ORDING INFORMATION

| Part Number | Package Type | Package Qty | Op Temp(°C) | Mark |
|-------------|--------------|-------------|-------------|--------|
| UC2501 | EMSOP8 | 3000 | -40~85 | UC2501 |
| UC2501 | ESOP8 | 3000 | -40~85 | UC2501 |



PINOUT



PIN FUNCTIONS

| NO. | NAME | TYPE ⁽¹⁾ | DESCRIPTION |
|-----|------|---------------------|---|
| 1 | GND | G | Ground connection |
| 2 | RSET | I | External resistor used to set current-limit threshold; |
| 3 | IN | P/I | Power supply/Input voltage connected to Power Switch; connect a 1 µF or greater ceramic capacitor from IN to GND as close to the IC as possible |
| 4 | ENB | I | Enable input, logic low turns on UC2501 |
| 5 | SEL | I | Logic-level control input; When it is high or floating, DP/DM operate in 2.1A mode, when it is Low, DP/DM operate in 2.4A mode; |
| 6 | DP | O/I | DP date line to connector, output for hand-shake voltage to portable equipment, high impedance while disabled |
| 7 | DM | O/I | DM data line to connector, input for hand-shake voltage from portable equipment high impedance while disabled |
| 8 | OUT | 0 | Power-switch output, connected to VBUS of USB; connect a 22µF or greater ceramic capacitor from OUT to GND as close to the IC as possible |

(1) G = Ground, I = Input, O = Output, P = Power

MARK INFORMATION





ABSOLUTE MAXIMUM RATINGS (1)

Over recommended operating free-air temperature range (unless otherwise noted)

| | MIN | MAX | UNIT | | |
|----------------------------------|--------------------------------------|------|------|----|--|
| Supply Voltage Range | IN | -0.3 | 7.0 | V | |
| Input voltage range | DP,DM | -0.3 | 5.8 | | |
| Continuous output sink current | DP input current, DM input current | | 35 | mA | |
| Continuous output source current | DP output current, DM output current | | 35 | | |
| ESD rating, Human Body | IN | | 2 | kV | |
| Model (HBM) | DP, DM | | 2 | KV | |
| Operating Junction Temperature | T _J | -40 | 125 | °C | |
| Storage Temperature Range | T _{stg} | -65 | 150 | ر | |

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| THERMAL METRIC | | | |
|----------------|---|----|-------|
| 0 | EMSOP8 Package thermal impedance ⁽¹⁾ | 65 | °C/W |
| θ_{JA} | ESOP8 Package thermal impedance ⁽¹⁾ | 42 | *C/VV |

⁽¹⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

| | PARAMETER | MIN | MAX | UNIT | |
|--------------------|--------------------------------|------|------|------|--|
| V _{IN} | Input voltage of IN | 4.5 | 6.5 | V | |
| V _{DP/DM} | DP data line input voltage | | 5.5 | V | |
| I _{DP/DM} | Continuous sink/source current | | ±10 | mA | |
| R _{SET} | Resistance of R _{SET} | 13 | 100 | kΩ | |
| I _{OUT} | Continuous sink/source current | 1000 | 4000 | mA | |
| TJ | Operating Junction Temperature | -40 | 125 | °C | |



ELECTRICAL CHARACTERISTICS

Conditions are: TA = 25° C, VIN = SEL = 5.0 V, ENB = GND and RSET = 33.0k Ω . Positive current are into pins. All voltages are with respect to GND (unless otherwise noted).

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|----------------------|--|------------------------------------|------|------|------|------|--|
| Power Switch | | | | | | | |
| | EMSOP8 Package | | | 45 | 68 | | |
| RDSON | ESOP8 Package | I _{OUT} =1A | | 55 | 83 | mΩ | |
| Tr | OUT voltage rise time | | 1.73 | | | | |
| Tf | OUT voltage fall time | 0: 4: 5 D: 400 0 | 0.8 | | | | |
| Ton | OUT voltage turn-on time | $C_L = 1 \mu F, R_L = 100 \Omega,$ | | 2.48 | | ms | |
| Toff | OUT voltage turn-off time | | | 2.98 | | | |
| Current Limit | | | | | | | |
| | | Rset=19.1k | 2.47 | 2.75 | 3.03 | | |
| los | OUT current limited | Rset=21.5k | 2.16 | 2.43 | 2.70 | A | |
| | | Rset=33.0k | 1.43 | 1.61 | 1.79 | | |
| Enable Pin (ENB |) | | | | | | |
| VENB | ENB threshold voltage, falling | | 0.8 | 1.33 | 2.3 | V | |
| V _{ENB_HYS} | Hysteresis | | | 150 | | mV | |
| R _{PD} | Pull Down Resistor | | 200 | 290 | 380 | kΩ | |
| Hiccup Mode | | | | | | | |
| Vout_short | OUT Threshold Voltage to enter Hiccup mode | | | 2.85 | | V | |
| Ton_HICCUP | ON Time of Hiccup mode | | 70 | 130 | 190 | ms | |
| Toff_HICCUP | OFF Time of Hiccup mode | | 0.7 | 1.3 | 1.9 | s | |
| Thermal Shutdo | wn | | | | | | |
| | Temperature Rising Threshold | | | 172 | | °C | |
| | Hysteresis | | | 20 | | | |



ELECTRICAL CHARACTERISTICS

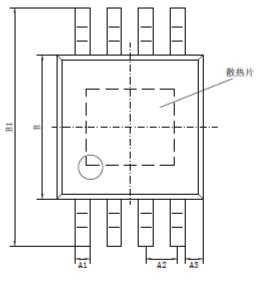
Conditions are: TA = 25° C, VIN = SEL = 5.0 V, ENB = GND and RSET = 19.1 k Ω . Positive current are into pins. All voltages are with respect to GND (unless otherwise noted).

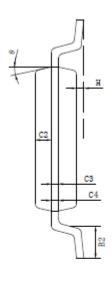
| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------------|--|------------------------|------|------|------|------|
| UNDERVOLTAGE L | OCKOUT | | | | | |
| VuvLo | IN rising UVLO threshold voltage | | 3.75 | 3.95 | 4.15 | V |
| | Hysteresis | | | 100 | | mV |
| SUPPLY CURRENT | | | • | | | |
| lin | IN supply current | VIN=5.0V, ENB=0V | | 160 | 280 | |
| I _{DDL} | IN Disable Supply Current | VIN=ENB=5.0V | | 0 | 2 | μΑ |
| BC 1.2 DCP MODE | (SHORT) | | | | | |
| RDPM_SHORT | DP / DM shorting resistance | | | 125 | 200 | Ω |
| RDCHG_SHORT | Resistors connected DP /DM to GND after hand-shaking | | | 200 | 400 | kΩ |
| V _{DPL_TH_DETACH} | DP low threshold while detaching BC1.2 devices | | 310 | 330 | 350 | mV |
| VDPL_TH_DETACH_HYS | hysteresis | | | 50 | | mV |
| IPAD MODE 2.1A M | ode (SEL=1 or Floating) | | • | | | • |
| V _{DP_IPAD} | DP output voltage | | 2.5 | 2.7 | 2.9 | V |
| V _{DM_IPAD} | DM output voltage | | 1.85 | 2.0 | 2.15 | V |
| R _{DP_IPAD} | DP output impedance | I _{DP} = -5uA | 20 | 30 | 40 | kΩ |
| R _{DM_IPAD} | DM output impedance | I _{DM} = -5uA | 20 | 30 | 40 | kΩ |
| IPAD MODE 2.4A M | ode (SEL=0) | | • | | | • |
| V _{DP_IPAD} | DP output voltage | | 2.5 | 2.7 | 2.9 | V |
| V _{DM_IPAD} | DM output voltage | | 2.5 | 2.7 | 2.9 | V |
| R _{DP_IPAD} | DP output impedance | I _{DP} = -5uA | 20 | 30 | 40 | kΩ |
| R _{DM_IPAD} | DM output impedance | I _{DM} = -5uA | 20 | 30 | 40 | kΩ |
| Galaxy Tab MODE | • | | | | | • |
| V _{DP_GAL} | DP output voltage | | 1.1 | 1.2 | 1.3 | V |
| V _{DM_GAL} | DM output voltage | | 1.1 | 1.2 | 1.3 | V |
| R _{DP_GAL} | DP output impedance | I _{DP} = -5uA | 70 | 105 | 140 | 1.0 |
| R _{DM_GAL} | DM output impedance | I _{DM} = -5uA | 70 | 105 | 140 | kΩ |

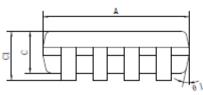


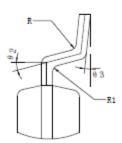
PACKAGE INFORMATION

EMSOP8





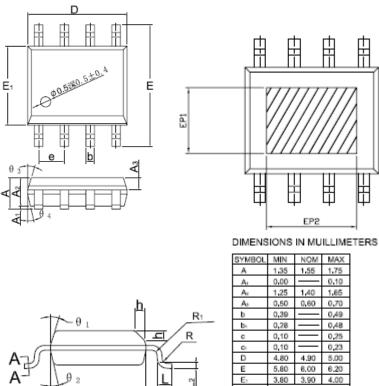


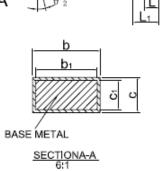


| 标注 | 最小(==) | 最大(100) | 标注 | 最小(==) | 最大(100) | | |
|-----------|---|---------|-----|----------|---------|--|--|
| A | 2.90 | 3.20 | C3 | 0. | 152 | | |
| A1 | 0.28 | 0.35 | C4 | 0.15 | 0.23 | | |
| A2 | 0.6 | 5TYP | H | 0.02 | 0.15 | | |
| A3 | 0.3 | 75TYP | θ | 12 | ° TYP4 | | |
| В | 2.90 | 3.20 | 0 1 | 12 | ° TYP4 | | |
| B1 | 4.70 | 5. 10 | 0.2 | 14 | ° TYP | | |
| B2 | 0.45 | 0.75 | 03 | 0° | ' ~ 6° | | |
| С | 0.75 | 0.95 | R | 0. | 15TYP | | |
| C1 | 1 | 1.10 | R1 | 0. 15TYP | | | |
| C2 | 0.3 | 28TYP | | | | | |
| * 注: EMSO | * 注: EMSOP8产品框架基岛尺寸为1.80X1.80, 散热片尺寸为1.80X1.55 (单位: mm) | | | | | | |



ESOP8





| Α | 1,35 | 1,55 | 1.75 |
|----------------|------|---------|------|
| Aı | 0.00 | | 0.10 |
| Az | 1.25 | 1.40 | 1,65 |
| A ₀ | 0,50 | 0,60 | 0.70 |
| Ф | 0,39 | | 0.49 |
| ğ | 0,28 | | 0,48 |
| 9 | 0,10 | | 0,25 |
| 9 | 0,10 | | 0,23 |
| D | 4.80 | 4.90 | 5.00 |
| E | 5.80 | 6.00 | 6.20 |
| E: | 3.80 | 3.90 | 4.00 |
| 6 | 1 | .27BSC | |
| L | 0.45 | | 1,00 |
| L | | 1,04REF | ! |
| L | 0 |).25BSC | ; |
| R | 0.07 | | |
| Ri | 0,07 | | |
| h | 0,3 | 0,4 | 0,5 |
| | O* | | 8° |
| 8 t | 11° | 17° | 19° |
| 0 : | 11° | 13° | 15° |
| 6.5 | 15° | 17* | 19* |
| 8. | 11° | 13" | 15* |
| EP1 | 2.40 | | |
| EP2 | 9.90 | | |